#### 506617751 04/19/2021

### PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6664558

| SUBMISSION TYPE:      | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT     |

#### **CONVEYING PARTY DATA**

| Name           | Execution Date |
|----------------|----------------|
| Ting-Yao Huang | 03/12/2021     |
| Po-Chih Wang   | 03/12/2021     |
| Ka-Un Chan     | 03/12/2021     |

#### **RECEIVING PARTY DATA**

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|-----------------|-----------------------------------|--|
| Street Address: | 2 Innovation Rd. II, Science Park |  |
| City:           | HsinChu                           |  |
| State/Country:  | TAIWAN                            |  |

#### **PROPERTY NUMBERS Total: 1**

| Property Type       | Number   |
|---------------------|----------|
| Application Number: | 17234760 |

#### **CORRESPONDENCE DATA**

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| ATTORNEY DOCKET NUMBER: | REAP1075USA |
|-------------------------|-------------|
| NAME OF SUBMITTER:      | SIBYL YU    |
| SIGNATURE:              | /SIBYL YU/  |
| DATE SIGNED:            | 04/19/2021  |

**Total Attachments: 6** 

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PATENT REEL: 055964 FRAME: 0427

# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

## Title of Invention: CONFIGURABLE OFFSET COMPENSATION DEVICE

| As the below named inventor, I hereby declare that: This declaration is directed to:  |  |                    |
|---|--|--------------------|
| ☑ The attached application, or  |  |                    |
| ☐ United States application number  | filed on   | , or               |
| ☐ PCT international application number  | filed on   |                    |
| The above-identified application was made or authorized to  | be made by me.   |                    |
| I believe that I am the original inventor or an original joint invapplication.  | entor of a claimed invention in t  | the                |
| I hereby acknowledge that any willful false statement made under18 U.S.C. 1001 by fine or imprisonment of not more th   | in this declaration is punishable an five (5) years, or both.  |                    |
| In consideration of the payment by Realtek Semicondu  | uctor Corp. having a pos   | tal address of     |
| 2 Innovation Rd. II, Science Park, HsinChu 30076  | i, Taiwan, R.O.C.  |                    |
| (referred to as "ASSIGNEE"below) to I of the sum of One Do acknowledged, andfor other good and valuable consideration   | ollar (\$ 1.00), the receipt of whicn.   | h is hereby        |
| I hereby sell, assign and transfer to ASSIGNEE and the succe<br>the entire right, title and interest in and to any and all improv-<br>invention as above-identified application and, in and to, all Lo<br>invention by the above application or any continuations, con-<br>substitutes, or extensions thereof, and as to Letters Patent a | ements which are disclosed in the etters Patent to be obtained for tinuation-in-part, divisions, repetitional forms. | he<br>said<br>wals |
| I hereby covenant that no assignment, sale, agreement or entered into which would conflict with this assignment;  | ncumbrance has been or will be   | made or            |
| I further covenant that ASSIGNEE will, upon its request, be pand documents relating to said invention and said Letters Paknown and accessible to I and will testify as to the same in a related thereto and will promptly execute and deliver to ASSI   | atent and legal equivalents as many interference, litigation process   | av ha              |
| representatives any and all papers, instruments or affidavits maintain, issue and enforce said application, said invention a equivalents thereof which may be necessary or desirable to IN WITNESS WHEREOF, I have hereunto set hand and sea  | and said Letters Patent and said<br>carry out the proposes thereof   | l                  |
| Note: An application data sheet (PTO/SB/14 or equivalent), i  | ncluding naming the entire   |                    |

Page 1 of 6

inventive entity, must accompany this form. Use this form for each additional inventor.

### Docket No REAP1075USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Ting-Yao Huang

Date: MAR 12 2021

Signature: Ting-Yao Huang

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NPO#REA-P1075-USA:0 CUST#108A-260US

F#NPO-P0002E-US1201 DSB0-108U042827

## COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

#### Title of Invention:

### CONFIGURABLE OFFSET COMPENSATION DEVICE

| As the below named inventor, I hereby declare that: This declaration is directed to:  The attached application, or  |                                    |  |  |
|---|------------------------------------|--|--|
| ☐ United States application number  | filed on , or                      |  |  |
| ☐ PCT international application number  |                                    |  |  |
| The above-identified application was made or authorized to be made by me.   |                                    |  |  |
| I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.  |                                    |  |  |
| I hereby acknowledge that any willful false statement made in this declaration is punishable under18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.  |                                    |  |  |
| In consideration of the payment by Realtek Semiconductor Co   | rp. having a postal address of     |  |  |
| 2 Innovation Rd. II, Science Park, HsinChu 30076, Taiwan  | , R.O.C.                           |  |  |
| (referred to as "ASSIGNEE"below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.   |                                    |  |  |
| I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof. |                                    |  |  |
| I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;  |                                    |  |  |
| I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal   |                                    |  |  |
| representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.  |                                    |  |  |
| Note: An application data sheet (PTO/SB/14 or equivalent), including n inventive entity, must accompany this form. Use this form for <u>each add</u>  | aming the entire itional inventor. |  |  |

## Docket No REAP1075USA

| LEGAL NAI  | WE OF INVENTOR(ASSIGNOR) |       |     |                 |
|------------|--------------------------|-------|-----|-----------------|
| Inventor:  | Po-Chih Wang             | Date: | MAR | 12 20 <b>21</b> |
| Signature: | 20 Chih Wang             |       |     |                 |

NPO#REA-P1075-USA:0 CUST#108A-260US Page 4 of 6

F#NPO-P0002E-US1201 DSB0-108U042827

## COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

## Title of Invention:

CONFIGURABLE OFFSET COMPENSATION DEVICE

| As the below named inventor, I hereby declare that: This declaration is directed to:  |  |
|---|--|
| ☑ The attached application, or  |  |
| ☐ United States application number  | filed on, or   |
| ☐ PCT international application number  | filed on   |
| The above-identified application was made or authorized to be   | made by me.  |
| I believe that I am the original inventor or an original joint inventapplication.   | tor of a claimed invention in the  |
| I hereby acknowledge that any willful false statement made in the under 18 U.S.C. 1001 by fine or imprisonment of not more than   | his declaration is punishable five (5) years, or both.   |
| In consideration of the payment by Realtek Semiconduct  | tor Corp. having a postal address of   |
| 2 Innovation Rd. II, Science Park, HsinChu 30076, T   | aiwan, R.O.C.  |
| (referred to as "ASSIGNEE" below) to I of the sum of One Dollar acknowledged, and for other good and valuable consideration.  | r (\$ 1.00), the receipt of which is hereby  |
| I hereby sell, assign and transfer to ASSIGNEE and the success the entire right, title and interest in and to any and all improvem invention as above-identified application and, in and to, all Letter invention by the above application or any continuations, continuations, or extensions thereof, and as to Letters Patent any | ents which are disclosed in the ers Patent to be obtained for said uation-in-part, divisions, renewals |
| I hereby covenant that no assignment, sale, agreement or encuentered into which would conflict with this assignment;  | imbrance has been or will be made or   |
| I further covenant that ASSIGNEE will, upon its request, be provand documents relating to said invention and said Letters Pater known and accessible to I and will testify as to the same in any related thereto and will promptly execute and deliver to ASSIGN  | nt and legal equivalents as may be interference, litigation proceeding                                 |
| representatives any and all papers, instruments or affidavits required maintain, issue and enforce said application, said invention and equivalents thereof which may be necessary or desirable to car IN WITNESS WHEREOF, I have hereunto set hand and seal the  | said Letters Patent and said   |
| Note: An application data sheet (PTO/SB/14 or equivalent), inclinventive entity, must accompany this form. Use this form for ea   | uding naming the entire  |

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#### Docket No REAP1075USA

| LEGAL NAME OF INVENTOR(ASSIGNOR) |            |                   |        |
|----------------------------------|------------|-------------------|--------|
| Inventor:                        | Ka-Un Chan | Date: MAR 12 2021 |        |
| Signature:                       | - Zo-la    | Char              | ****** |

NPO#REA-P1075-USA:0 CUST#108A-260US

**RECORDED: 04/19/2021** 

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F#NPO-P0002E-US1201 DSB0-108U042827

PATENT REEL: 055964 FRAME: 0433